

**Holtek Semiconductor Inc.**  
**2023 Annual Shareholders' Meeting Notice**  
**(Summary Translation)**

1. The 2023 Annual Shareholders' Meeting (hereinafter as "Meeting") will be convened at the Edison, HSP link (No.1, Gongye E. 2<sup>nd</sup> Rd., East Dist., Hsinchu City 300, Taiwan (R.O.C.)) at 9:00 a.m., Taiwan Time, on May 24, 2023 (Wednesday). Shareholder attendance registrations will be accepted starting from 08:30 a.m. and the registration place for attendance will be the same as the conference place.

The agenda of the Meeting is as follows:

A. Reporting Items

- a. 2022 Business Report
- b. Audit Committee's Review Report
- c. Report on 2022 Employees' and Directors' Remuneration

B. Approval Items

- a. Adoption of the 2022 Business Report and Financial Statements
- b. Adoption of the 2022 Earnings Distribution

C. Discussion Items and Election

- a. Amendment to the Company's "Articles of Incorporation"
- b. Amendment to the "Rules and Procedures of Shareholders' Meeting"
- c. Amendment to the "Procedures for Acquisition or Disposal of Assets and Financial Derivatives Transactions"
- d. By-election of one Seat of Directors, hereby submitted for election.
- e. Permit directors to engage in competitive conduct

D. Extemporaneous Motions

2. The major items of the proposal for distribution of 2022 profits adopted at Board of Directors meeting are as follows:
  - A. Total amount of cash distributed to shareholders: NT\$904,672,800. Each common shareholder will be entitled to receive a cash dividend of NT\$4 per share.
  - B. The record date will be decided by the Board of Directors authorized by the Shareholders' Meeting.
3. Pursuant to Article 172 of the Company Act, essential contents shall be posted on the website of Market Observation Post System (<https://emops.twse.com.tw/server-java/t58query>), enter the Security Code to select an e-book, then choose annual financial and stockholders' report.

4. Pursuant to Article 165 of the Company Act, share transfer registration for the company will be suspended from March 26, 2023 to May 24, 2023.
5. One copy of sign-in card and proxy attendance form are attached to this meeting notice. To attend the Meeting in person, please sign or stamp on the attendance notice and submit it in person at the Meeting on the scheduled meeting date. To attend by proxy, please sign or stamp on the proxy attendance form and personally fill out the name and address of the agent, then deliver it to the Transfer Agency Department of Sinopac Securities Corporation at least five (5) days prior to the meeting date. The sign-in card for the agent will be posted accordingly.
6. Shareholders, solicitors or agents attending the Meeting shall show the documents of identification for verification only.
7. If a proxy is solicited by the shareholder(s), the company is required to compile details on the proxy solicitation parties and disclose such information on the Securities & Futures Institute (SFI) website no later than April 21, 2023. Shareholder(s) can obtain information on the "Free proxy disclosure & related information system" (<https://free.sfi.org.tw>) with Security Code: 6202.
8. The shareholders may cast electronic votes at the Meeting, of which the electronic voting period will be from April 22, 2023 to May 21, 2023. Please login the “electronic voting platform for shareholders’ meeting” on the website of Taiwan Depository & Clearing Corporation and cast votes in accordance with the instruction. (<https://www.stockvote.com.tw>)
9. There shall be an election of one (1) board members. The election of board members is conducted through a nomination process, and the list of candidate for director is as follows: Mr. Ming-Kung, Wang. For other relevant information relating to the candidate for director, please refer to the website (<http://mops.twse.com.tw>).
10. The Transfer Agency Department of SinoPac Securities Corporation is the proxy tallying and verification institution for the Meeting.
11. These regulations should be abided and applied.

Sincerely,

Board of Directors  
Holtek Semiconductor Inc.